

SOT1268

plastic thermal enhanced ultra thin small outline package; no leads; 6 terminals; body: 1.4 mm x 1.2 mm x 0.47 mm

9 December 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	DFN1412-6
Package type industry code	DFN1412-6
Package style descriptive code	USON (ultra thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	2-9-2016
Manufacturer package code	SOT1268

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.35	-	1.4	1.45	mm
E	package width	1.15	-	1.2	1.25	mm
A	seated height	0.44	-	0.47	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	6	-	



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2. Package outline

DFN1412-6: plastic thermal enhanced ultra thin small outline package; no leads; 6 terminals; body: 1.4 x 1.2 x 0.47 mm

SOT1268

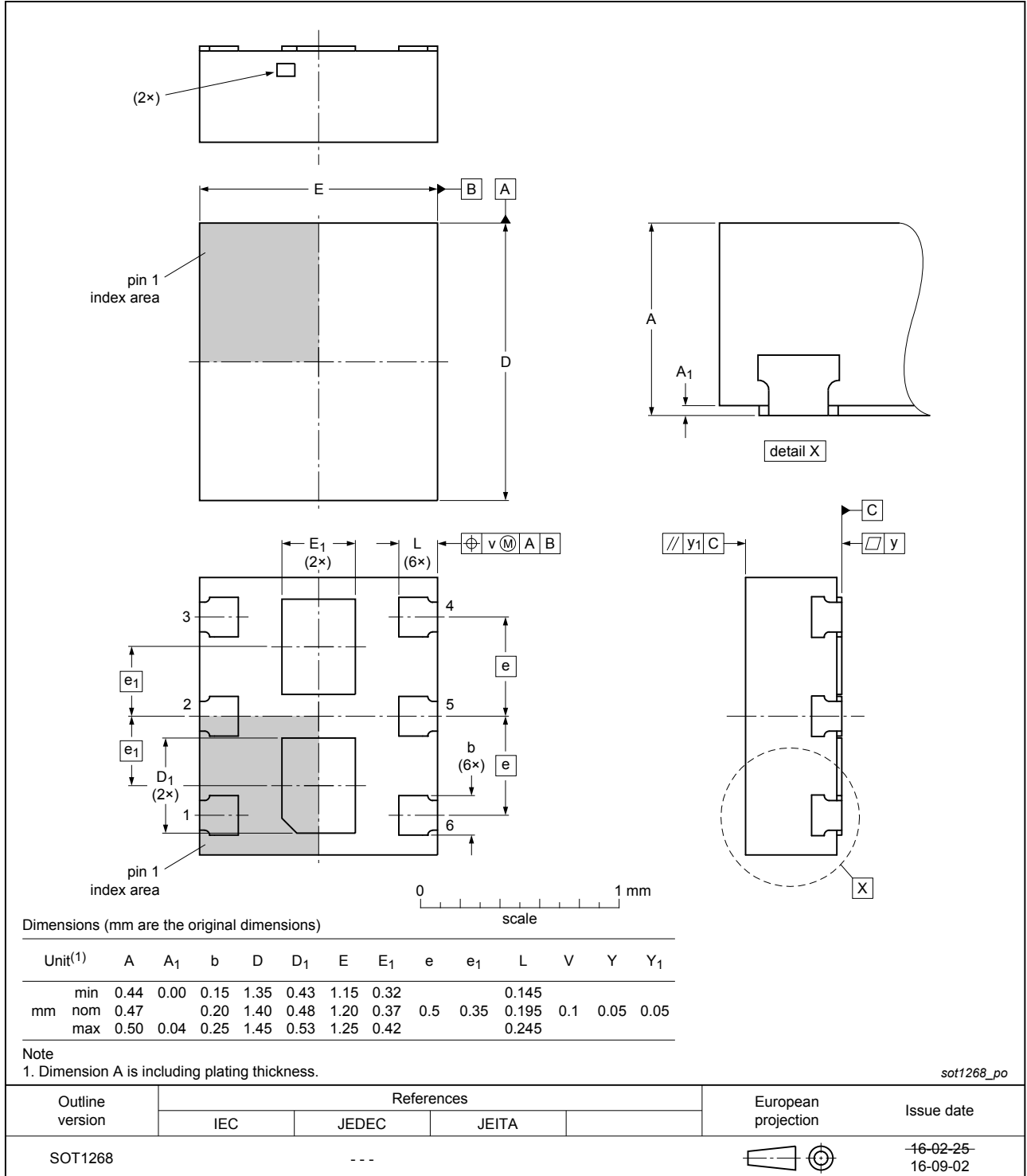


Fig. 1. Package outline DFN1412-6 (SOT1268)

3. Soldering

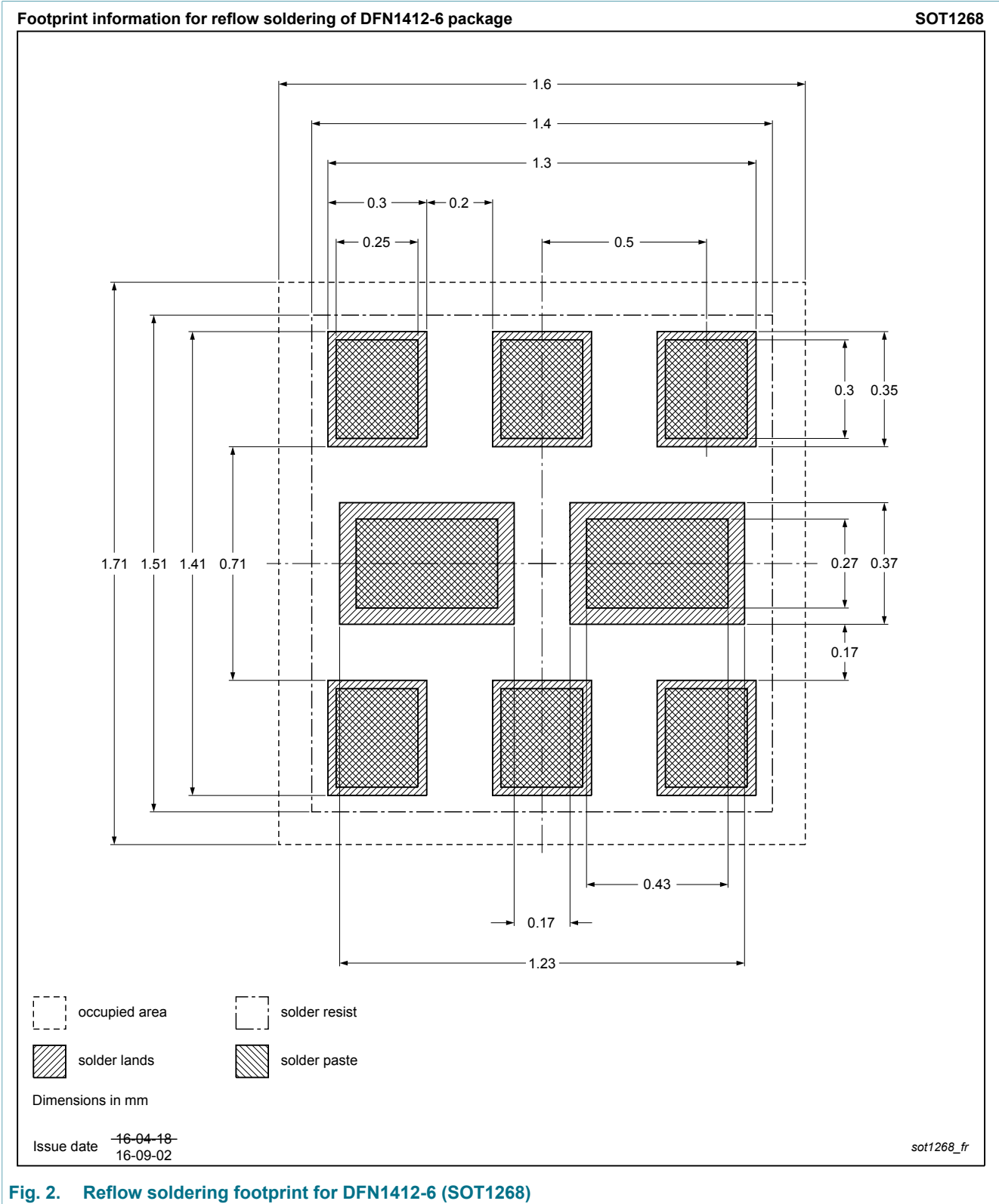


Fig. 2. Reflow soldering footprint for DFN1412-6 (SOT1268)

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4. Legal information

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